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STN) & USPAT - Update  
(FILE 'USPATFULL' ENTERED AT 15:41:28 ON 12 APR 2002)

L1 277 S (CMP OR POLISH? OR CHEMIMECH? OR PLANARIZ? OR LAP? OR GRIND?  
L2 1509 S (CMP OR POLISH? OR CHEMIMECH? OR PLANARIZ? OR LAP? OR GRIND?  
L3 1765 S L1 OR L2  
L4 SET HIGH OFF  
476 S L3 AND (SEMICONDUCT? OR WAFER# OR CHIP#)  
SET HIGH ON  
L5 476 S L3 AND L4  
L6 116 S L1 AND L5  
L7 33 S L6 AND (CMP OR POLISH? OR CHEMIMECH? OR PLANARIZ? OR LAP? OR  
L8 83 S L6 NOT L7  
L9 161 S L1 NOT (L7 OR L8)  
L10 6 S L9 AND (CMP OR POLISH? OR CHEMIMECH? OR PLANARIZ? OR LAP? OR  
L11 155 S L9 NOT L10  
SET HIGH OFF  
L12 365 S L2 AND (SEMICONDUCT? OR WAFER# OR CHIP#)  
SET HIGH ON  
L13 365 S L2 AND L12  
L14 360 S L13 NOT L1  
SET HIGH OFF  
L15 2 S L14 AND MASS?(3A)SPEC?  
SET HIGH ON  
L16 2 S L14 AND L15

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